HiPerFRED

DSEP60-12AR

V_{RRM}	=	1200 V
I _{FAV}	=	60 A
t _{rr}	=	40 ns

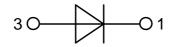
High Performance Fast Recovery Diode Low Loss and Soft Recovery Single Diode

Part number

DSEP60-12AR



Backside: isolated **E**72873



Features / Advantages:

- Planar passivated chips
- Very low leakage current
- Very short recovery time
- Improved thermal behaviour
- Very low Irm-values
- Very soft recovery behaviour
- Avalanche voltage rated for reliable operation
- Soft reverse recovery for low EMI/RFI
- Low Irm reduces:
 - Power dissipation within the diode
- Turn-on loss in the commutating switch

Applications:

- Antiparallel diode for high frequency switching devices
- Antisaturation diode
- Snubber diode
- Free wheeling diode Rectifiers in switch mode power
 - supplies (SMPS)
- Uninterruptible power supplies (UPS)

Package: ISOPLUS247

- Isolation Voltage: 3600 V~
- Industry standard outline
- RoHS compliant
- Epoxy meets UL 94V-0
 - Soldering pins for PCB mounting
 - Backside: DCB ceramic
 - Reduced weight
 - Advanced power cycling

Terms Conditions of usage:

The data contained in this product data sheet is exclusively intended for technically trained staff. The user will have to evaluate the suitability of the product for the intended application and the completeness of the product data with respect to his application. The specifications of our components may not be considered as an assurance of component characteristics. The information in the valid application- and assembly notes must be considered. Should you require product information in excess of the data given in this product data sheet or which concerns the specific application of your product, please contact your local sales office. Due to technical requirements our product may contain dangerous substances. For information on the types in question please contact your local sales office. Should you intend to use the product in aviation, in health or life endangering or life support applications, please notify. For any such application we urgently recommend

to perform joint risk and quality assessments;
the conclusion of quality agreements;

- to establish joint measures of an ongoing product survey, and that we may make delivery dependent on the realization of any such measures.

IXYS reserves the right to change limits, conditions and dimensions.

Data according to IEC 60747and per semiconductor unless otherwise specified

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DSEP60-12AR

Fast Diode			Ratings				
Symbol	Definition	Conditions		min.	typ.	max.	Unit
V _{RSM}	max. non-repetitive reverse block	ing voltage	$T_{VJ} = 25^{\circ}C$			1200	V
V _{RRM}	max. repetitive reverse blocking v	oltage	$T_{VJ} = 25^{\circ}C$			1200	V
I _R	reverse current, drain current	V _R =1200 V	$T_{VJ} = 25^{\circ}C$			650	μA
		V _R =1200 V	$T_{vJ} = 150^{\circ}C$			2.5	mA
VF	forward voltage drop	I _F = 60 A	$T_{vJ} = 25^{\circ}C$			2.66	V
		I _F = 120 A				3.18	V
		I _F = 60 A	T _{vJ} = 150°C			1.81	V
		I _F = 120 A				2.40	V
I FAV	average forward current	$T_c = 85^{\circ}C$	T _{vJ} = 175°C			60	Α
		rectangular d = 0.5					
V _{F0}	threshold voltage		T _{vJ} = 175°C			1.08	V
r _F	slope resistance } for power lo	oss calculation only				9.4	mΩ
R _{thJC}	thermal resistance junction to cas	е				0.65	K/W
R _{thCH}	thermal resistance case to heatsi	nk			0.25		K/W
P _{tot}	total power dissipation		$T_c = 25^{\circ}C$			230	W
I _{FSM}	max. forward surge current	t = 10 ms; (50 Hz), sine; $V_R = 0 V$	$T_{vJ} = 45^{\circ}C$			500	Α
C	junction capacitance	$V_{R} = 600 V f = 1 MHz$	$T_{VJ} = 25^{\circ}C$		30		pF
I _{RM}	max. reverse recovery current	N N	$T_{VJ} = 25 \degree C$		13		Α
		$I_{\rm F} = 60 \text{A}; V_{\rm R} = 600 \text{V}$	T _{vJ} = 100 °C		20		А
t _{rr}	reverse recovery time	-di _F /dt = 200 A/µs	$T_{VJ} = 25 ^{\circ}C$		80		ns
)	T _{VJ} = 100 °C		220		ns

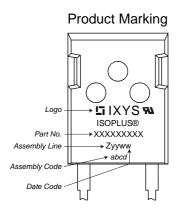
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DSEP60-12AR

Package ISOPLUS247			1	Ratings			
Symbol	Definition	Conditions		min.	typ.	max.	Unit
I _{RMS}	RMS current	per terminal				70	А
T _{vJ}	virtual junction temperature			-55		175	°C
T _{op}	operation temperature			-55		150	°C
T _{stg}	storage temperature			-55		150	°C
Weight					6		g
F _c	mounting force with clip			20		120	Ν
d _{Spp/App}	creepage distance on surface	l striking distance through air	terminal to terminal	5.4			mm
d _{Spb/Apb}	creepage distance on surface p	Striking distance through an	terminal to backside	4.1			mm
V	isolation voltage	t = 1 second		3600			V
		t = 1 minute	50/60 Hz, RMS; liso∟ ≤ 1 mA	3000			V



Ordering	Ordering Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	DSEP60-12AR	DSEP60-12AR	Tube	30	481939

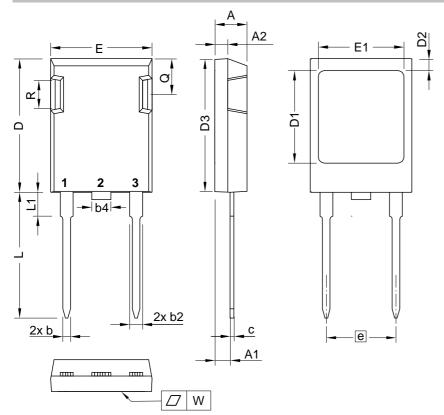
Similar Part	Package	Voltage class
DSEP60-12A	TO-247AD (2)	1200
DHG60I1200HA	TO-247AD (2)	1200
DSEP60-12B	TO-247AD (2)	1200

Equiva	alent Circuits for	Simulation	* on die level	T _{VJ} = 175 °C
) □ R ₀	Fast Diode		
V _{0 max}	threshold voltage	1.08		V
$R_{0 max}$	slope resistance *	6.8		mΩ

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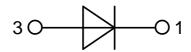
Outlines **ISOPLUS247**



Dim.	Millimeter		Inches		
Dim.	min	max	min	max	
Α	4.83	5.21	0.190	0.205	
A1	2.29	2.54	0.090	0.100	
A2	1.91	2.16	0.075	0.085	
b	1.14	1.40	0.045	0.055	
b2	1.91	2.20	0.075	0.087	
b4	2.92	3.24	0.115	0.128	
С	0.61	0.83	0.024	0.033	
D	20.80	21.34	0.819	0.840	
D1	15.75	16.26	0.620	0.640	
D2	1.65	2.15	0.065	0.085	
D3	20.30	20.70	0.799	0.815	
Е	15.75	16.13	0.620	0.635	
E1	13.21	13.72	0.520	0.540	
е	10.90 BSC		0.429 BSC		
L	19.81	20.60	0.780	0.811	
L1	3.81	4.38	0.150	0.172	
Q	5.59	6.20	0.220	0.244	
R	4.25	5.50	0.167	0.217	
W	-	0.10	-	0.004	

Die konvexe Form des Substrates ist typ. < 0.04 mm über der Kunststoffoberfläche der Bauteilunterseite The convex bow of substrate is typ. < 0.04 mm over plastic surface level of device bottom side

Die Gehäuseabmessungen entsprechen dem Typ TO-247 AD gemäß JEDEC außer Schraubloch und L_{max} . This drawing will meet all dimensions requiarement of JEDEC outline TO-247 AD except screw hole and except L_{max} .



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